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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Tongbi Jiang et al.

**Serial No.:** 09/483,712

**Filed:** January 14, 2000

**For:** CHIP-SCALE PACKAGES HAVING  
ENCAPSULATED CARRIER BONDS  
(As Amended)

**Examiner:** M. Warren

**Group Art Unit:** 2815

**Attorney Docket No.:** 3815US (98-0670)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

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**AMENDMENT UNDER 37 C.F.R. §1.116**

Box AF  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed January 29, 2002, the three-month shortened statutory period for response to which expires on March 29, 2002. This response is submitted on or before two months from the mailing date of the Final Office Action.

**IN THE CLAIMS:**

Applicants propose to amend claim 1 herein. Please note that all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity. Also attached is a version with markings to show the proposed changes made to the claims.